

**UT3P03Z**

Preliminary

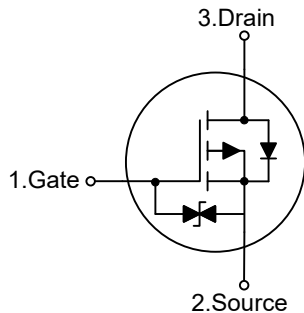
Power MOSFET

**-3.0A, -30V P-CHANNEL
POWER MOSFET****DESCRIPTION**

The **UT3P03Z** uses UTC advanced technology to provide excellent $R_{DS(ON)}$, low gate charge and operated with low gate voltages. This device can be applied to general-purpose switching devices applications.

FEATURES

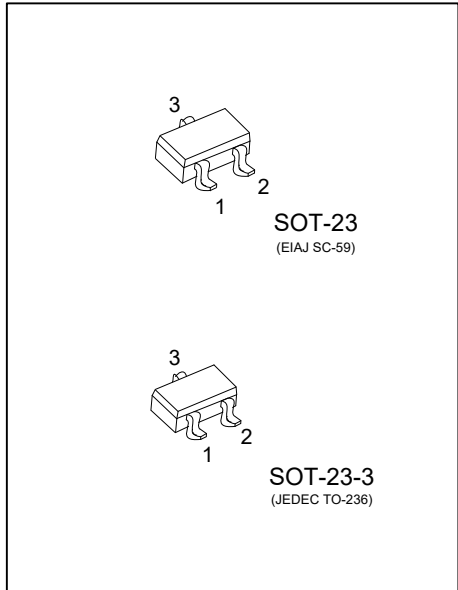
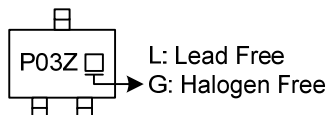
- * $R_{DS(ON)} \leq 100 \text{ m}\Omega$ @ $V_{GS} = -10\text{V}$, $I_D = -1.5\text{A}$
- * $R_{DS(ON)} \leq 140 \text{ m}\Omega$ @ $V_{GS} = -4.5\text{V}$, $I_D = -1.5\text{A}$
- * Fast Switching Capability
- * Avalanche Energy Specified
- * Improved dv/dt Capability, High Ruggedness

SYMBOL**ORDERING INFORMATION**

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
UT3P03ZL-AE2-R	UT3P03ZG-AE2-R	SOT-23-3	G	S	D	Tape Reel
UT3P03ZL-AE3-R	UT3P03ZG-AE3-R	SOT-23	G	S	D	Tape Reel

Note: Pin Assignment: G: Gate S: Source D: Drain

UT3P03ZG-AE2-R		
(1) Packing Type		(1) R: Tape Reel
(2) Package Type		(2) AE2: SOT-23-3, AE3: SOT-23
(3) Green Package		(3) G: Halogen Free and Lead Free, L: Lead Free

MARKING

■ **ABSOLUTE MAXIMUM RATING** ($T_C=25^{\circ}\text{C}$ unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	-30	V
Gate-Source Voltage		V_{GSS}	± 20	V
Drain Current	DC	I_D	-3	A
	Pulsed (Note 2)	I_{DM}	-6	A
Peak Diode Recovery dv/dt (Note 3)		dv/dt	1.2	V/ns
Power Dissipation ($T_C=25^{\circ}\text{C}$)	SOT-23	P_D	1.3	W
	SOT-23-3		1	W
Junction Temperature		T_J	+150	$^{\circ}\text{C}$
Storage Temperature Range		T_{STG}	-55 ~ +150	$^{\circ}\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature.

■ **THERMAL DATA**

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient	SOT-23	θ_{JA}	96	$^{\circ}\text{C/W}$
	SOT-23-3		65	$^{\circ}\text{C/W}$

Note: Device mounted on FR-4 substrate P_C board, 2oz copper, with 1inch square copper plate.

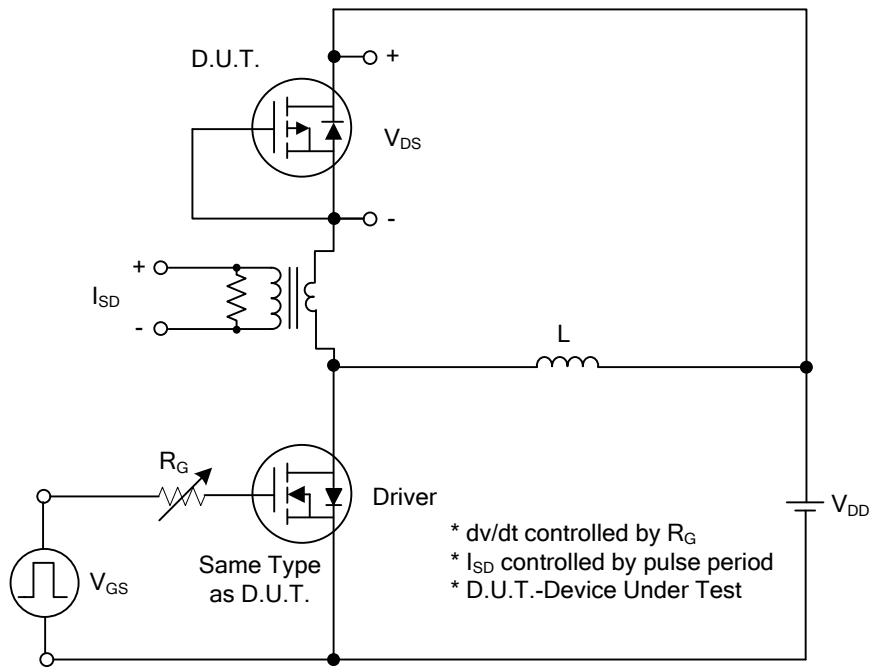
■ **ELECTRICAL CHARACTERISTICS** ($T_A=25^\circ\text{C}$ unless otherwise specified)

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV _{DSS}	V _{GS} =0V, I _D =-250μA	-30			V
Drain-Source Leakage Current		I _{DSS}	V _{DS} =-30V, V _{GS} =0V			-10	μA
Gate-Source Leakage Current	Forward	I _{GSS}	V _{GS} =+20V, V _{DS} =0V			+10	μA
	Reverse		V _{GS} =-20V, V _{DS} =0V			-10	μA
ON CHARACTERISTICS							
Gate Threshold Voltage		V _{GS(TH)}	V _{DS} = V _{GS} , I _D =-250μA	-1.0		-2.5	V
Static Drain-Source On-State Resistance		R _{DS(ON)}	V _{GS} =-10V, I _D =-1.5A			100	mΩ
			V _{GS} =-4.5V, I _D =-1.5A			140	mΩ
DYNAMIC PARAMETERS							
Input Capacitance		C _{ISS}	V _{GS} =0V, V _{DS} =-25V, f=1.0MHz		380		pF
Output Capacitance		C _{OSS}			84		pF
Reverse Transfer Capacitance		C _{RSS}			55		pF
SWITCHING PARAMETERS							
Total Gate Charge		Q _G	V _{DS} =-24V, V _{GS} =-10V, I _D =-3A , I _G =-1mA (Note 1, 2)		12		nC
Gate to Source Charge		Q _{GS}			3.1		nC
Gate to Drain Charge		Q _{GD}			2.2		nC
Turn-ON Delay Time		t _{D(ON)}	V _{DD} =-15V, V _{GS} =-10V, I _D =-3A, R _G =3Ω (Note 1, 2)		6		ns
Rise Time		t _R			17		ns
Turn-OFF Delay Time		t _{D(OFF)}			33		ns
Fall-Time		t _F			26		ns
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS							
Maximum Continuous Drain-Source Diode Forward Current		I _S				-3	A
Maximum Pulsed Drain-Source Diode Forward Current		I _{SM}				-6	A
Diode Forward Voltage (Note 1)		V _{SD}	I _F =-3A, V _{GS} =0V			-1.4	V
Body Diode Reverse Recovery Time (Note 1)		t _{rr}	I _S =-3A, V _{GS} =0V,		122		ns
Body Diode Reverse Recovery Charge		Q _{rr}	dl _F /dt =100A/μs		100		nC

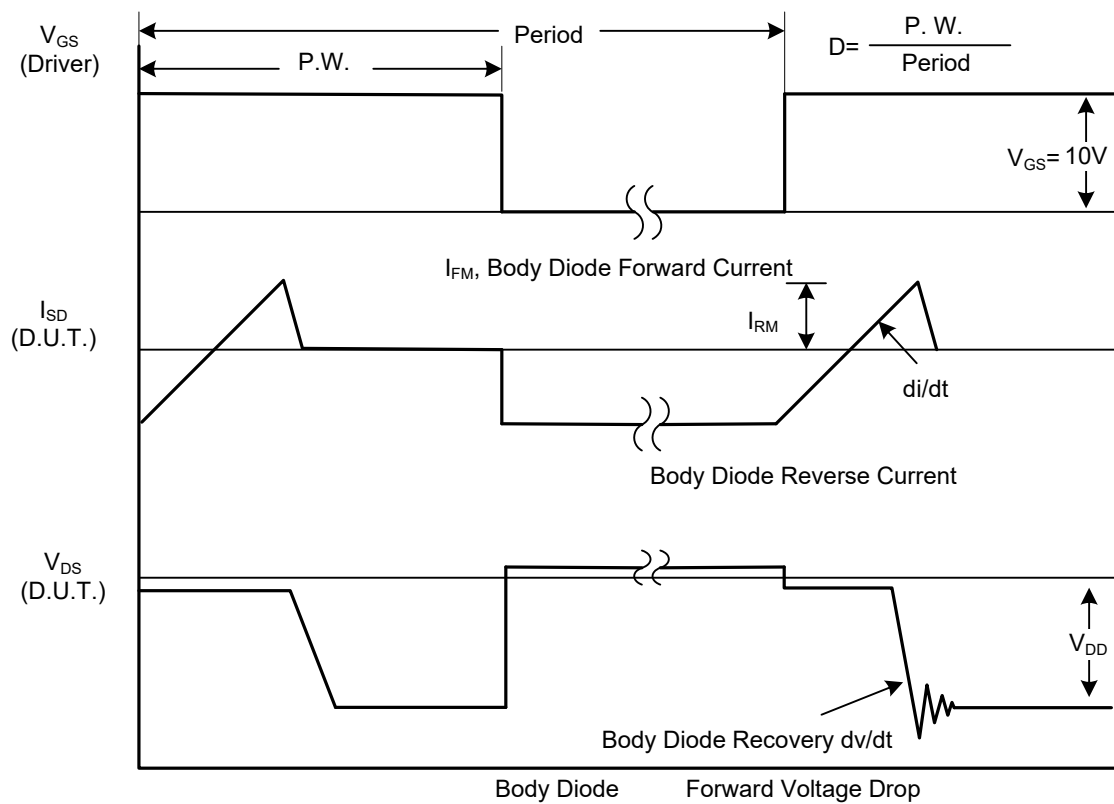
Notes: 1. Pulse Test: Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$.

2. Essentially independent of operating temperature.

■ TEST CIRCUITS AND WAVEFORMS

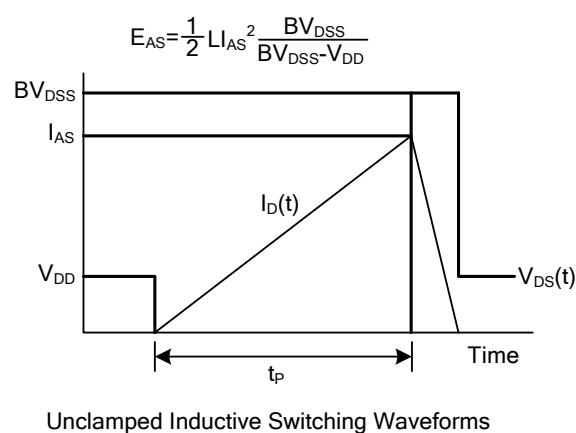
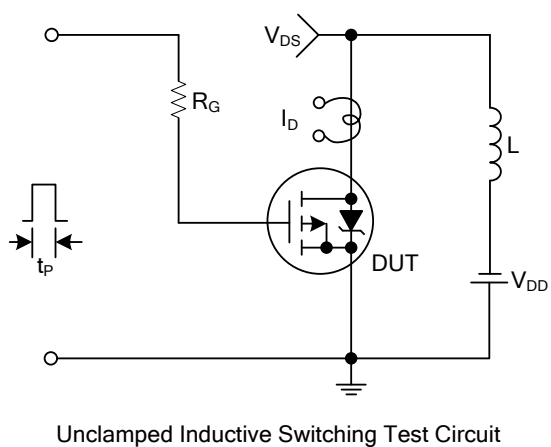
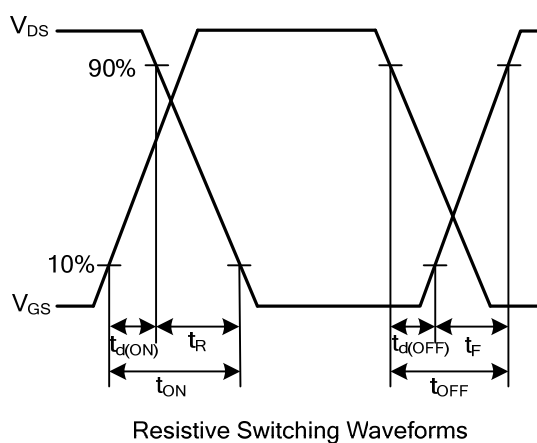
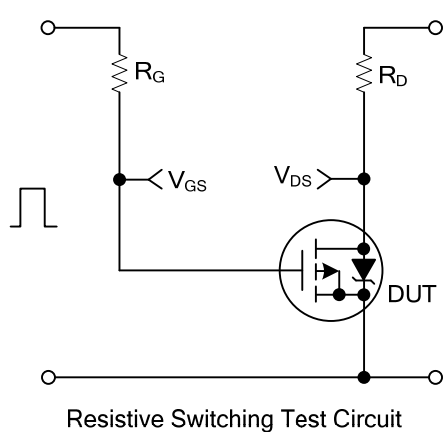
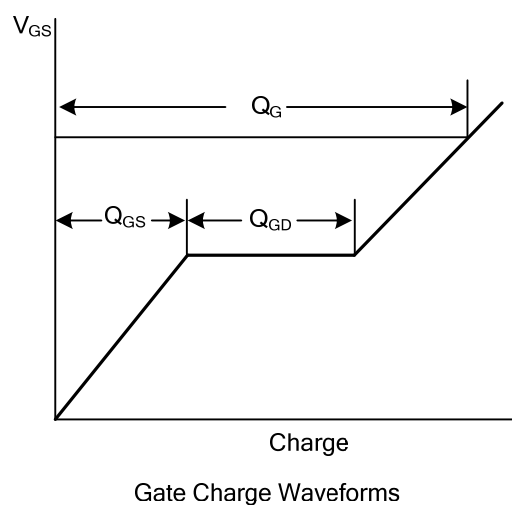
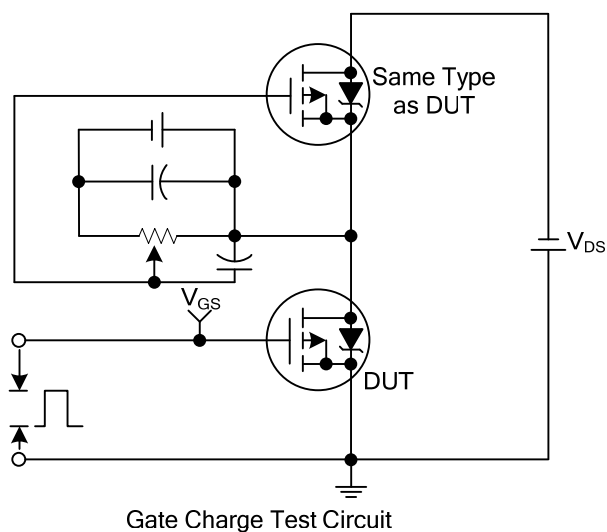


Peak Diode Recovery dv/dt Test Circuit



Peak Diode Recovery dv/dt Waveforms

■ TEST CIRCUITS AND WAVEFORMS



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